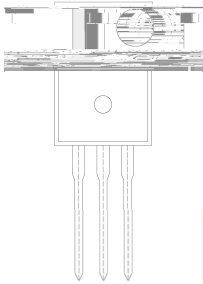


TO-220S

Ultrafast Recovery Diode in a TO-220S Plastic Package.

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

For high frequency, high voltage, high current rectifier diode, freewheeling diode.



PIN1 Anode

PIN 2 Cathode

PIN 3 Anode

PIN 4 NC

MURJ1620CT

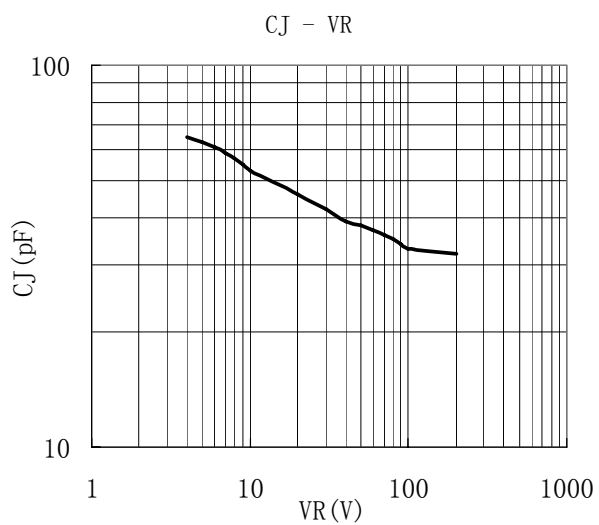
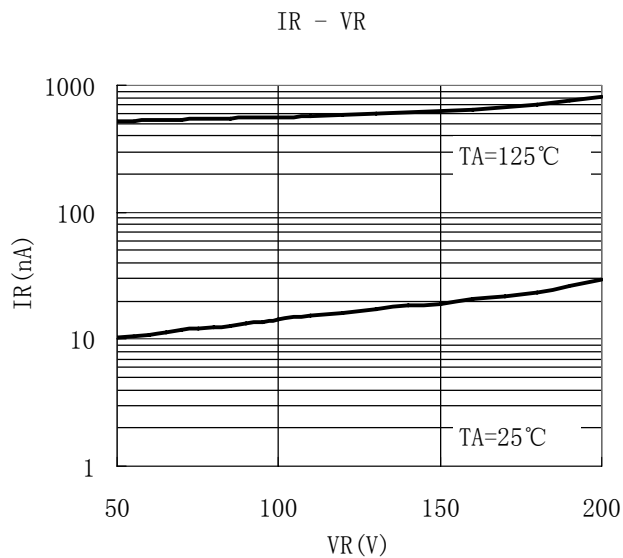
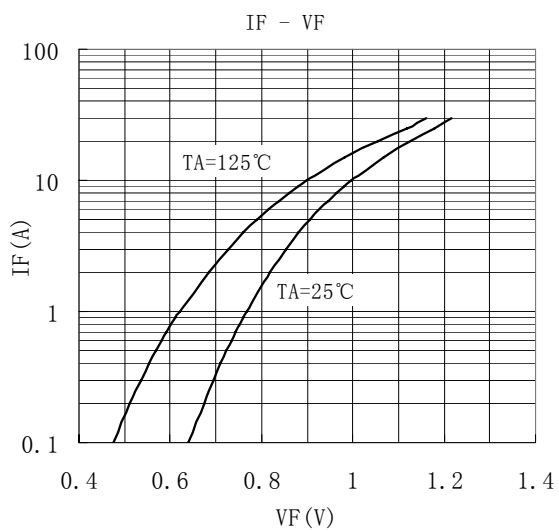
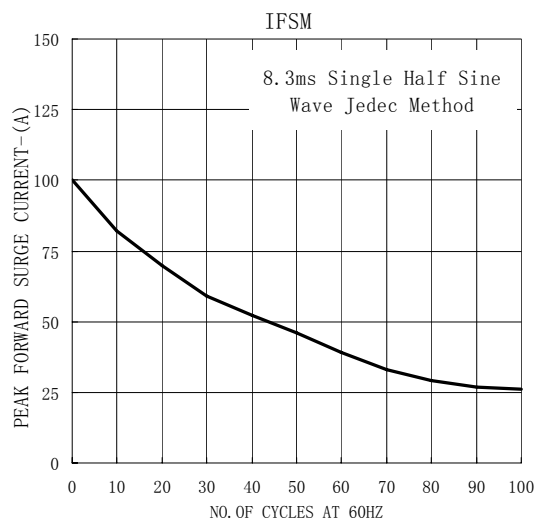
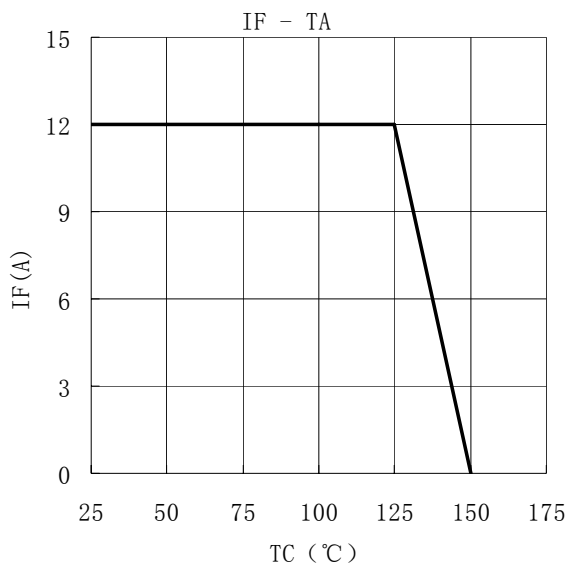
Rev.E Mar.-2016

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
RMS Voltage	V_{RMS}	140	V
DC Blocking Voltage	V_{DC}	200	V
Average Rectified Forward Current	I_F	2×8	A
Non Repetitive Peak Surge Current	I_{FSM}	120	A
Thermal Resistance Junction to Case	$R_{\theta JC}$	2.9	/W
Junction Temperature Range	T_J	150	
Storage Temperature Range	T_{stg}	-55~150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=2A$ $T_c=25^{\circ}C$		0.80		V
		$I_F=2A$ $T_c=125^{\circ}C$		0.66		V
		$I_F=8A$ $T_c=25^{\circ}C$		0.93	1	V
		$I_F=8A$ $T_c=125^{\circ}C$		0.82	0.9	V

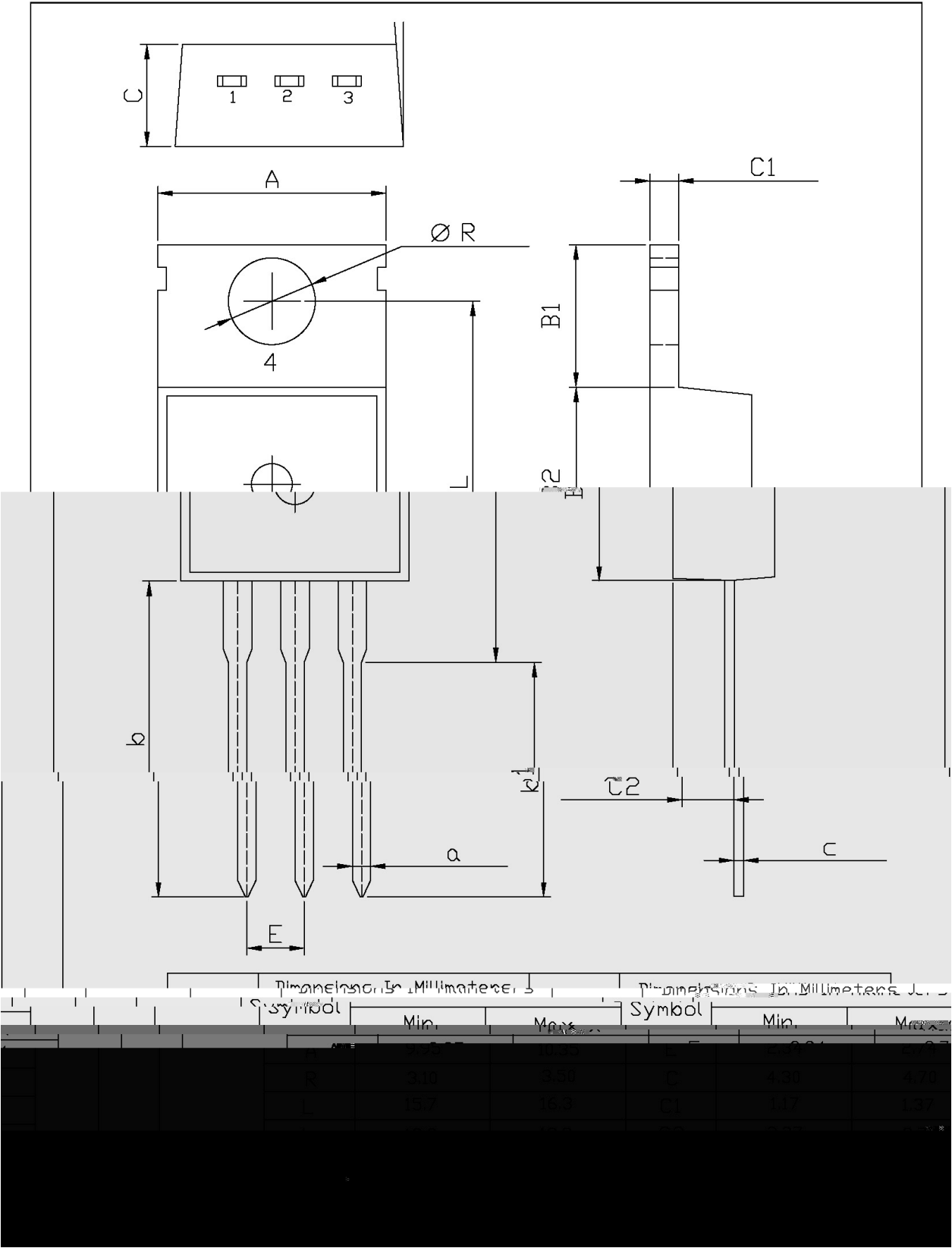
Instantaneous Reverse Current I_R
(Note 1)

/ Electrical Characteristic Curve

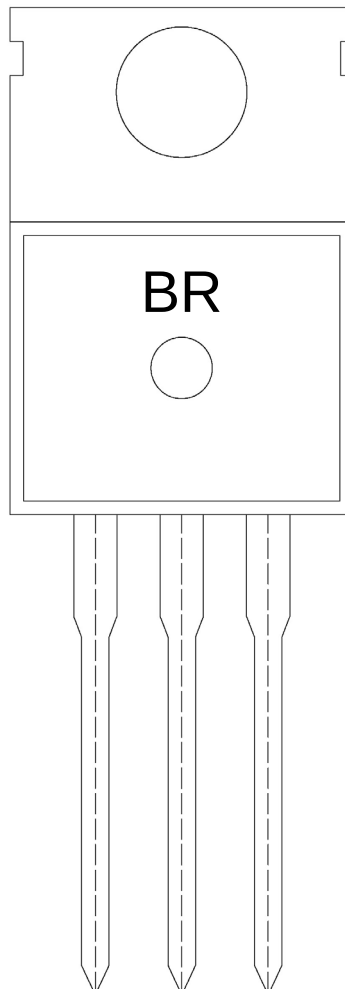


/ Package Dimensions

TO-220S Unit: mm



/ Marking Instructions



BR

MURJ1620

CT:

Note:

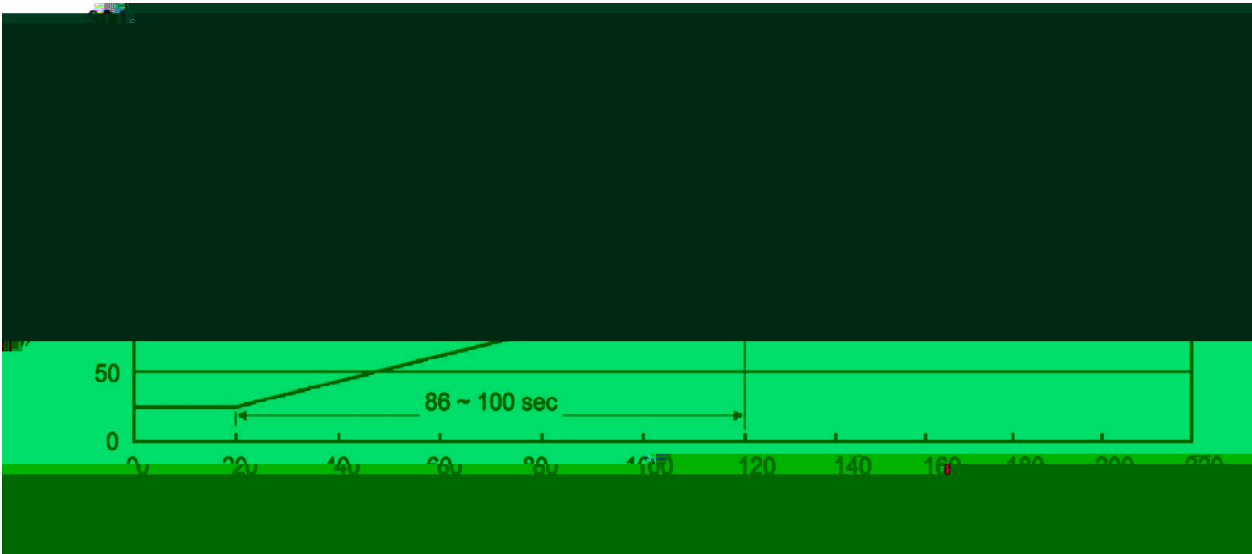
BR: Company Code

MURJ1620 Product Type.

CT: Internal Structure

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10

/sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:255±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp.:270±5

Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type	Units					Dimension		(unit mm ³)

/ Notices